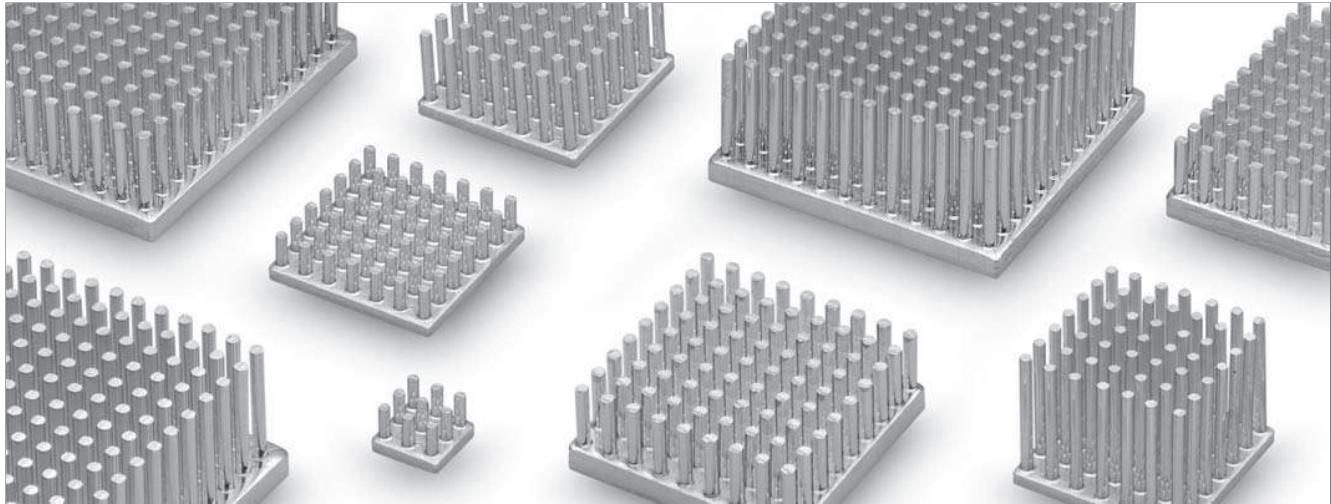


Pin heatsinks



- arrangement and number of pins for optimum air flow
- suitable for forced and free convection
- excellent thermal conductivity by the alloy material (Al99,5; 220 W/mK) and homogeneous arrangement of materials
- constant heat distribution in the base and the pins, in the direction of heat flow
- low weight achieved by optimised geometry
- Components fastened using glue, adhesive foil or clamps

customer-specific modifications and special designs; other pin-lengths and surfaces on request

surface: Al-natural

<p>art. no.</p> <p>ICK S 10 x 10 x 6,5 WLF ... 10 x 10 weight: 1 g</p>		
<p>art. no.</p> <p>ICK S 10 x 10 x 12,5 WLF ... 10 x 10 weight: 1.3 g</p>		
<p>art. no.</p> <p>ICK S 14 x 14 x 6,5 WLF ... 14 x 14 weight: 1.5 g</p>		

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Pin heatsinks

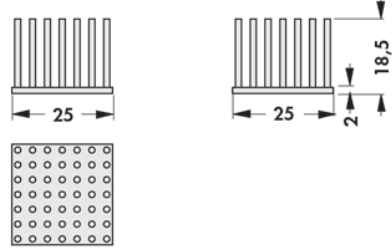
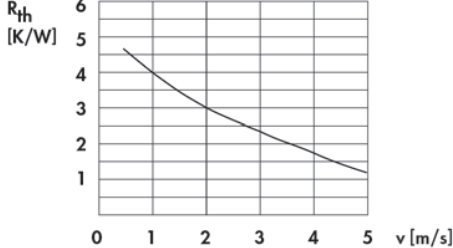
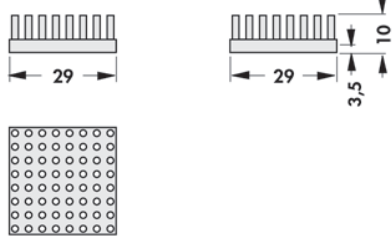
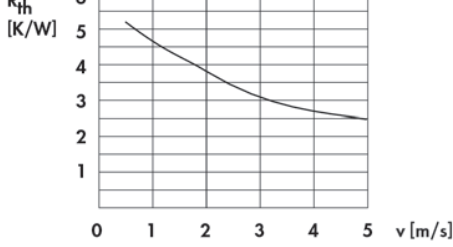
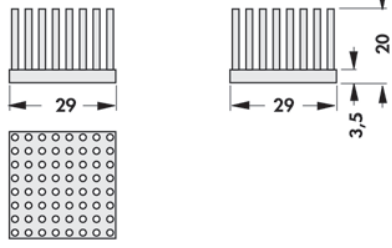
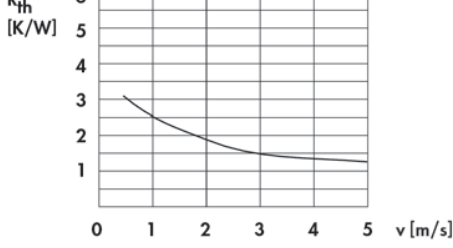
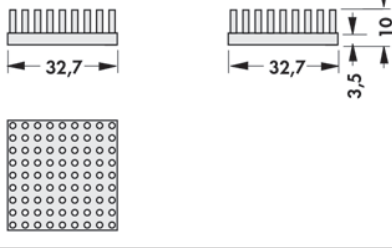
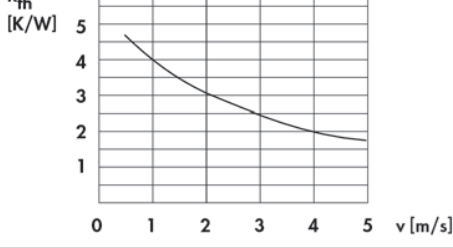
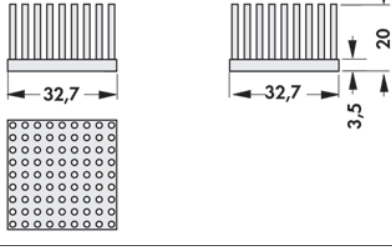
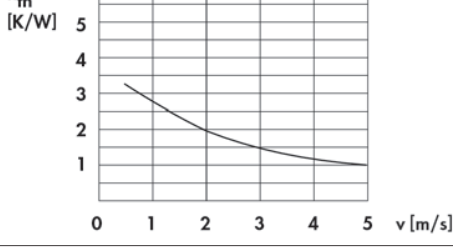
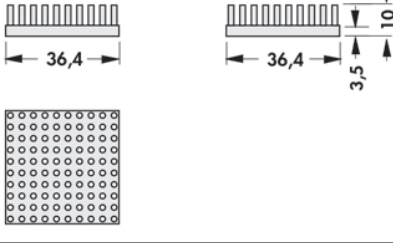
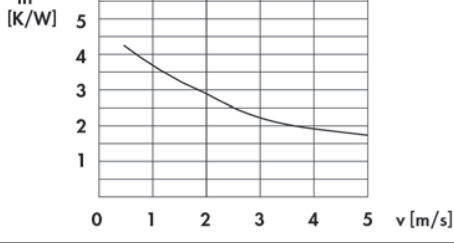
<p>art. no.</p> <p>ICK S 14 x 14 x 10 WLF ... 14 x 14 weight: 1.9 g</p>		
<p>art. no.</p> <p>ICK S 17 x 17 x 15 WLF ... 17 x 17 weight: 4.7 g</p>		
<p>art. no.</p> <p>ICK S 17 x 17 x 20 WLF ... 17 x 17 weight: 5.6 g</p>		
<p>art. no.</p> <p>ICK S 18 x 18 x 6,5 WLF ... 18 x 18 weight: 2.5 g</p>		
<p>art. no.</p> <p>ICK S 18 x 18 x 10 WLF ... 18 x 18 weight: 3.1 g</p>		
<p>art. no.</p> <p>ICK S 25 x 25 x 6,5 WLF ... 25 x 25 weight: 4 g</p>		
<p>art. no.</p> <p>ICK S 25 x 25 x 12,5 WLF ... 25 x 25 weight: 6 g</p>		

B 21

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Pin heatsinks

<p>art. no.</p> <p>ICK S 25 x 25 x 18,5 WLF ... 25 x 25 weight: 7 g</p>		
<p>art. no.</p> <p>ICK S 29 x 29 x 10 WLF ... 29 x 29 weight: 11 g</p>		
<p>art. no.</p> <p>ICK S 29 x 29 x 20 WLF ... 29 x 29 weight: 15 g</p>		
<p>art. no.</p> <p>ICK S 32 x 32 x 10 WLF ... 32 x 32 weight: 14 g</p>		
<p>art. no.</p> <p>ICK S 32 x 32 x 20 WLF ... 32 x 32 weight: 19 g</p>		
<p>art. no.</p> <p>ICK S 36 x 36 x 10 WLF ... 36 x 36 weight: 17 g</p>		

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Pin heatsinks

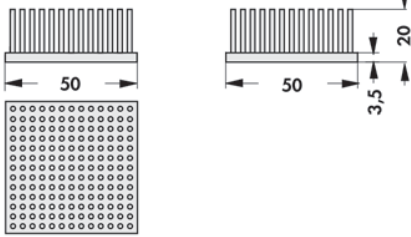
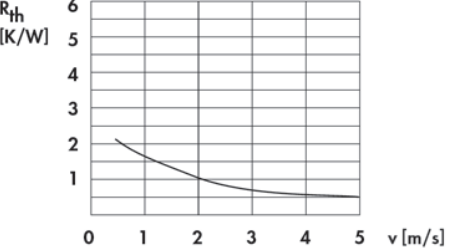
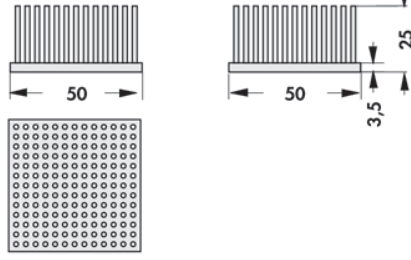
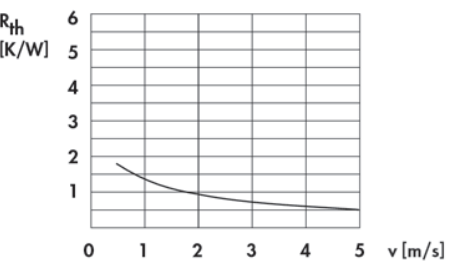
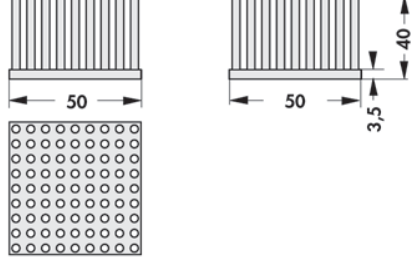
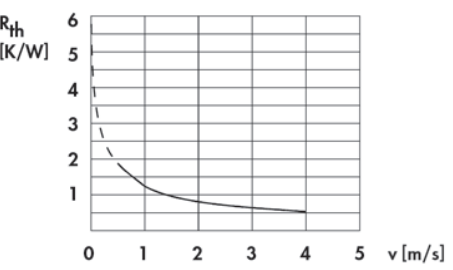
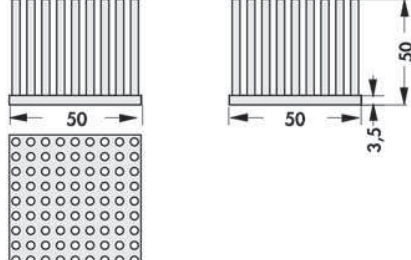
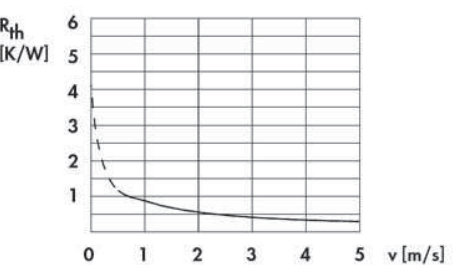
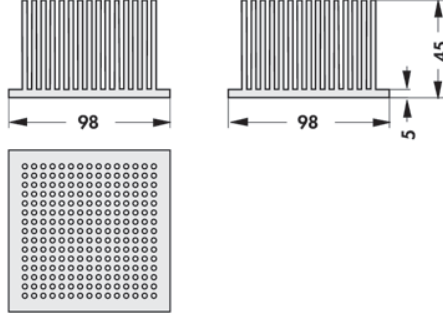
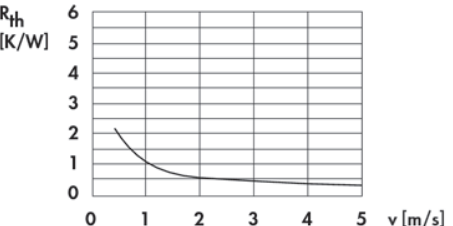
<p>art. no.</p> <p>ICK S 36 x 36 x 15 WLF ... 36 x 36 weight: 20 g</p>		
<p>art. no.</p> <p>ICK S 36 x 36 x 20 WLF ... 36 x 36 weight: 24 g</p>		
<p>art. no.</p> <p>ICK S 40 x 40 x 10 WLF ... 40 x 40 weight: 21 g</p>		
<p>art. no.</p> <p>ICK S 40 x 40 x 20 WLF ... 40 x 40 weight: 29 g</p>		
<p>art. no.</p> <p>ICK S 45 x 45 x 10 WLF ... 45 x 45 weight: 26 g</p>		
<p>art. no.</p> <p>ICK S 45 x 45 x 20 WLF ... 45 x 45 weight: 36 g</p>		

B 23

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Pin heatsinks

<p>art. no.</p> <p>ICK S 50 x 50 x 20 WLF ... 50 x 50 weight: 43 g</p>		
<p>art. no.</p> <p>ICK S 50 x 50 x 25 WLF ... 50 x 50 weight: 49 g</p>		
<p>art. no.</p> <p>ICK S 50 x 50 x 40 WLF ... 50 x 50 weight: 80.05 g</p>		
<p>art. no.</p> <p>ICK S 50 x 50 x 50 WLF ... 50 x 50 weight: 95.51 g</p>		
<p>art. no.</p> <p>ICK S 98 x 98 x 45 WLF ... 98 x 98 weight: 301.3 g</p>		

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